

Code:I Yellow (AlGaInP)

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--|-----------------|------------------|------|------|------|------|
| Forward Voltage (Per dice) | Vf | If=20mA | 1.8 | | 2.3 | V |
| Reverse Voltage (Per dice) | Vr | Ir=10uA | | 5 | | V |
| Luminous Intensity (Per dice) | Iv | If=20mA | | 50 | | mcd |
| Spectrum Width Of Half Value | $\Delta\lambda$ | If=20mA | | 30 | | nm |
| Wavelength | D λ | If=20mA | 585 | | 590 | nm |
| Peak Forward Current (Per dice) 1/10 Duty Cycle,0.1ms Pulse | Ifp | | 70 | | | mA |
| Operating Temperature Range | Topr | - 35 °C to 85 °C | | | | |
| Storage Temperature Range | Tstg | - 35 °C to 85 °C | | | | |
| Solder Temperature 1.5mm below seating plane for 3 Seconds at 260 °C | | | | | | |

Absolute Maximum Rating at Ta=25°C

Fig.1

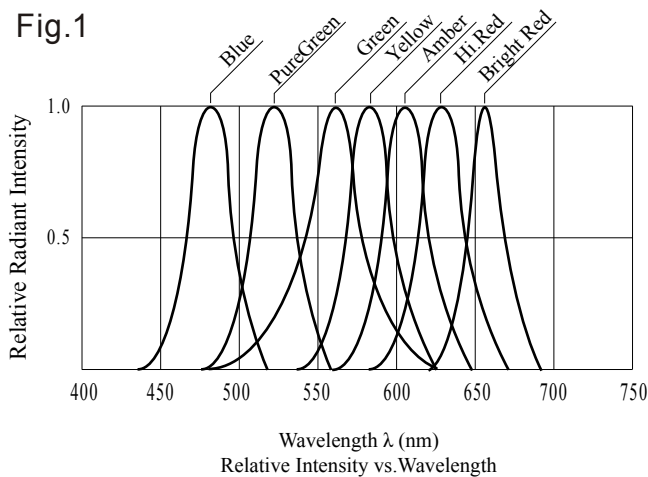


Fig.2

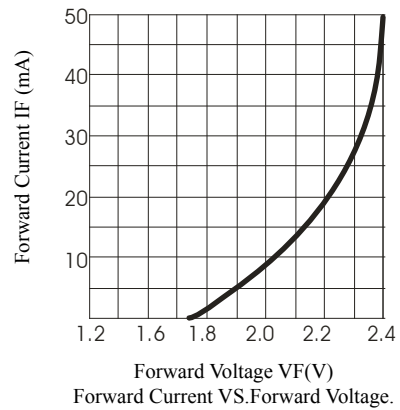


Fig.3

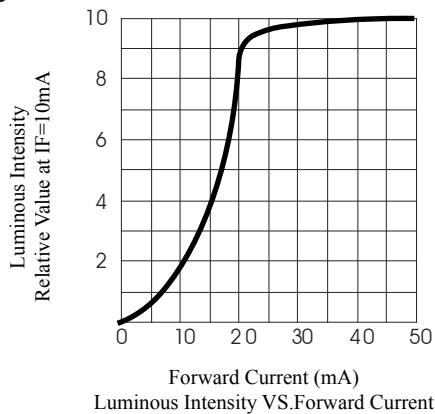
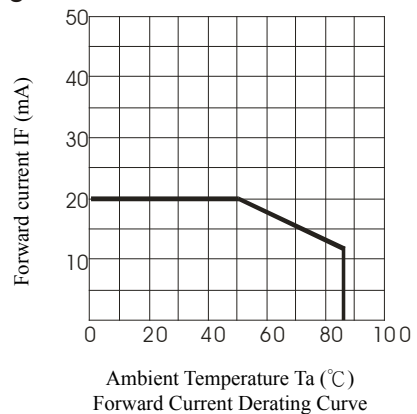
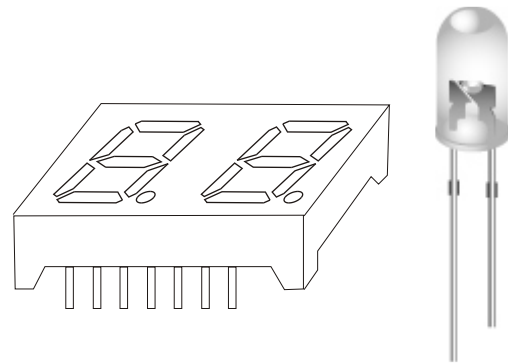
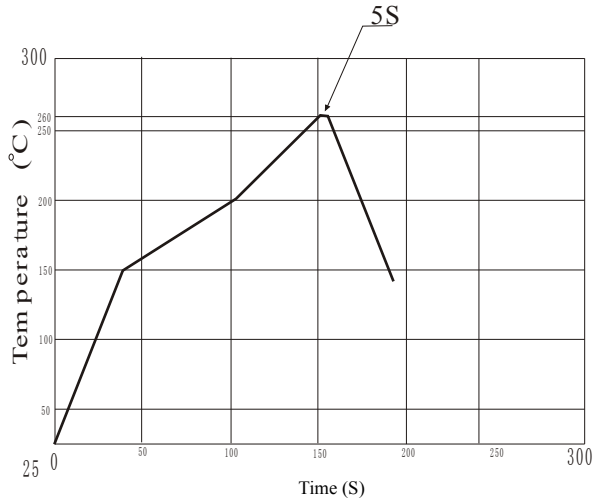


Fig.4



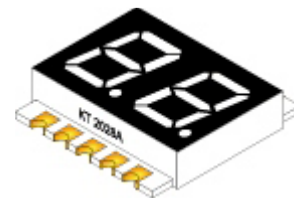
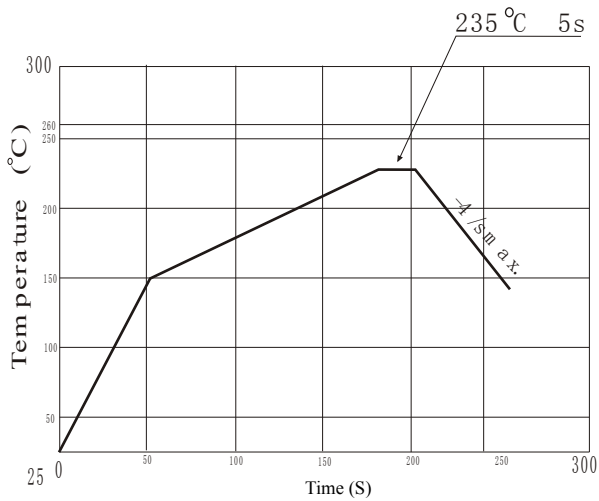
Wave Soldering for Lead-Free Through-hole LED



1.5mm below package base

| | |
|--------------------|---------------------|
| Solder Temperature | 260°C for 5 Seconds |
|--------------------|---------------------|

Lead-free SMT process



| | |
|-------------------------|---------------------|
| Lead solder Temperature | 235°C for 5 Seconds |
|-------------------------|---------------------|

Notes: Recommend the wave temperature max. 235 °C.
 Do not apply stress on the epoxy when temperature over 80 °C.
 No more than once.